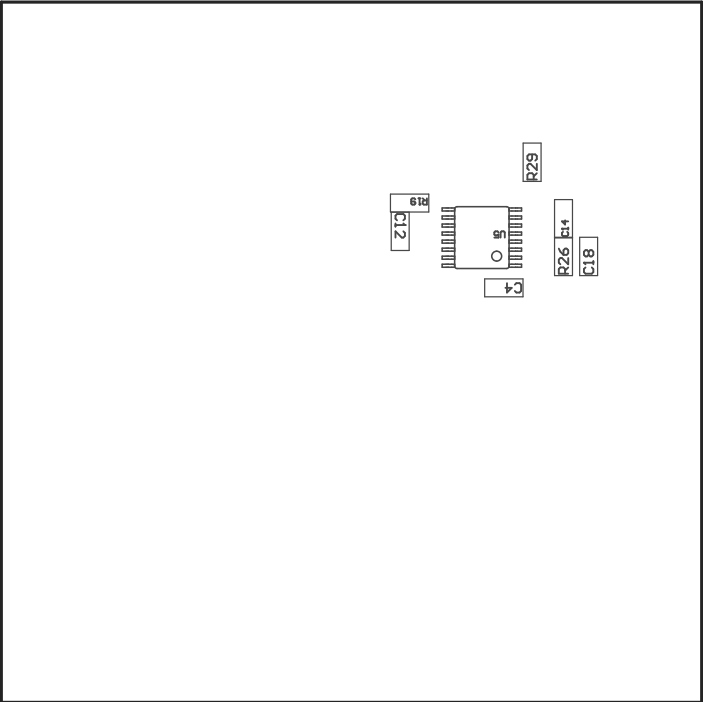


COMPONENTS MARKED "DNP" SHOULD NOT BE POPULATED.

ASSEMBLY DRAWING:

001

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA08007	REV: E1	SUN REV: Not In VersionControl
	TID #: TIDA-080007		
PLOT NAME = Top Assembly Drawing	GENERATED : 5/16/2018 4:20:23 PM		TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA08007	REV: E1	SUN REV: Not In VersionControl
	TID #: TIDA-080007		
PLOT NAME = Bottom Assembly Drawing	GENERATED: 5/16/2018 4:20:25 PM		TEXAS INSTRUMENTS

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